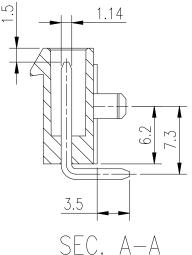


PCB LAYOUT COMPONENT SIDE



NOTES:

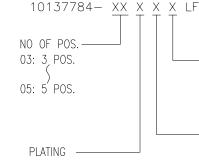
- 1. HSG MATERIAL: UL94V-O, MATERIAL AND COLOR: OPTIONAL
- 2. CONTACT MATERIAL: HIGH CONDUCTIVITY COPPER ALLOY
- 3. CONTACT FINISH: UNDERPLATING: Ni.

CONTACT AREA AND SOLDER TAILS: OPTIONAL.

- 4. PRODUCT SPECIFICATION: GS-12-1333
- 5. PACKAGE SPECIFICATION: GS-14-2362
- 6. THIS PART MATES WITH FCI RECEPTACLE WIRE CONNECTOR 10136644
- 7. THE PART IS APPLICABLE FOR WAVE SOLDERING PROCESS WITH A 1.0~1.6mm THICKNESS PCB. LCP HSG IS CAPABLE FOR 260°C, 5 SEC. REFLOW SOLDERING PROCESS.
- 8. DIMENSION TABLE

POS.	А	В
03	13.8	8.4
04	18.0	12.6
05	22.2	16.8

PART NUMBER SCHEME:



HSG MATERIAL/GLOW WIRE COMPATIBLE

- 1. PA66, COMPATIBLE
 2. PA66, NON COMPATIBLE
 3. LCP, COMPATIBLE
 4. LCP, NON COMPATIBLE

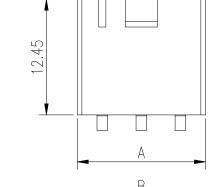
HSG COLOR

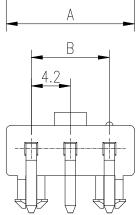
1. NATURAL 2. BLACK (NOT AVAILABLE FOR HSG

1. TIN `MATERIAL OPTION 1) 2. GOLD FLASH

3. 15u" Au, TIN ON TAILS 4. 30u" Au, TIN ON TAILS

mat	mat'l. code				surf	surface /tolerance				pro.	jecti	tion product family											
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ltr	ecn	no	dr	date	tolera	tolerances unless othe				therwise specified			J	title									
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she	et	revi	sion	Α																			
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PDS: Rev :A 3

form: A4mmXLc

STATUS:Released Printed: Jan 1342016